

REMARKS

This application has been carefully reviewed in light of the Office Action dated June 23, 2005. Claims 1 to 4 are in the application, of which Claim 1 is still the only independent claim. Reconsideration and further examination are respectfully requested.

Claims 1 and 4 were rejected under 35 U.S.C. § 103(a) over U.S. Patent 6,560,256 (Seki) in view of U.S. Patent 6,757,311 (Abe), and claims 2 and 3 were rejected further in view of U.S. Patent 5,625,189 (McCaul)^{1/}. The rejections are respectfully traversed.

The invention relates to a multilaser device which emits a plurality of laser beams from a respective plurality of laser chips. In conventional devices, each of the plurality of laser beams output by the device can vary greatly from laser beam to laser beam. This leads to a problem of deterioration in quality.

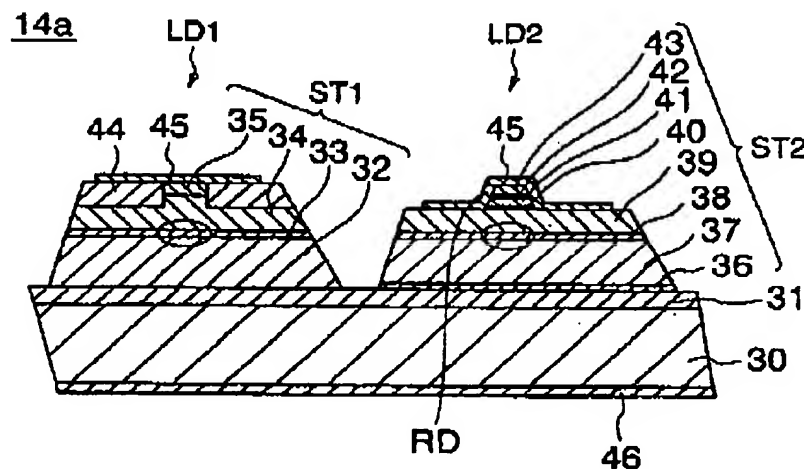
On the other hand, characteristics of laser beams emitted from laser chips produced from the same wafer lot often closely resemble each other, because the layered structure of such chips is similar. In recognition of this, the inventor herein produced a multilaser device in which a second laser chip is produced from the same wafer lot as that of a first laser chip.

^{1/}The technological disclosure of Seki is being treated as prior art for purposes of this Amendment.

The Office Action concedes that the citation to Seki does not disclose laser chips from the same wafer lot, and Claim 1 has been amended so as to emphasize this characteristic feature of the invention.

In entering the rejection of Claim 1, the Office Action relied on Abe, and took the position that Abe's Figure 5A discloses laser chips that are produced from one and the same wafer lot. Inspection of Abe's Figure 5A, however, reveals that the layered structure of the laser chips are quite different from each other. That is, as seen in Abe's Figure 5A (reproduced below), laser chip ST1 exhibits a layered structure that is fundamentally different from that of laser chip ST2, such that it is impossible to conclude that these two laser chips are produced from the same wafer lot:

FIG. 5A

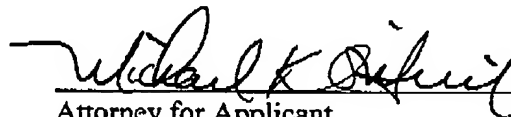


As such, Abe does not disclose at least the feature that the second laser chip is produced from the same wafer lot as that of the first laser chip, as recited in independent Claim 1.

McCaul has been reviewed, but is not seen to disclose or to suggest anything pertinent to the above discussion of Abe and Seki. Accordingly, allowance of Claim 1 is respectfully requested.

Applicant's undersigned attorney may be reached in our Costa Mesa, California office at (714) 540-8700. All correspondence should continue to be directed to our below-listed address.

Respectfully submitted,



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